



FG324 - 63/37 (Sn/Pb) Solder Balls
 FGG324 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS			NOTES
	MIN.	NOM.	MAX.	
A	\approx	\approx	2.50	2
A ₁	0.40	0.50	0.60	
D/E	23.00 BSC			
D ₁ /E ₁	21.00 REF			
e	1.00 BSC			
ϕ_b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.35	
ddd	\approx	\approx	0.30	
eee	\approx	\approx	0.10	
M	22			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAJ-1

324-BALL FINE-PITCH BGA, 1.00MM PITCH (FG324/FGG324)